

Information for Lot 9 of ErP (Ecodesign)

This addendum addresses European Union (EU) Ecodesign requirements for servers and storage products. All data and ratings within this addendum are in reference only to the Supermicro product(s) in the manual. The below information conforms to requirements laid down in Annex II of the Commission Regulation 2019/424.

- 3(1)(a): See Section 1.1 of the system manual for the product type.
- 3(1)(b): See the title page and preface of the system manual for the trademark and manufacturer's address.
- 3(1)(c): See the title page of the system manual for product model number(s).
- 3(1)(d): See the serial number on the physical system to determine the year of manufacture.
- 3(1)(e-j): **PSU Efficiency and Power Factor Value (Table) (From 80 Plus report)**

PSU Model #: PWS-2K08A-1R Watts: 2000W	PSU Efficiency				Power Factor
	10 %	20 %	50 %	100 %	
% of Rated Load	92.8 %	94.89 %	96.09 %	94.53 %	0.99
Single Output (AC-DC)					

System (EUT) Efficiency in **Idle State** Power (Table)

Representative Configurations	Measured Idle State Power (W)	Calculated Idle Power Allowance (W)
High-End Performance Configuration	274.9	1401.17
Typical Configuration	N/A	N/A
Low-End Performance Configuration	287.4	929.31

System (EUT) Efficiency in **Active State** Power (Table)

Representative Configurations	Active State Efficiency Score (Effserver)	Minimum Active State Efficiency for 1-Socket Server
High-End Performance Configuration	108	9
Typical Configuration	N/A	
Low-End Performance Configuration	73.9	

3(1)(k): The operating condition class is **A2**.

Operating condition class	Dry bulb temp °C		Humidity range, non-condensing		Max dew point (°C)	Maximum rate of change (°C/hr)
	Allowable range	Recommended range	Allowable range	Recommended range		
A1	15- 32	18-27	- 12 °C Dew Point (DP) and 8 % relative humidity (RH) to 17 °C DP and 80 % RH	- 9 °C DP to 15 °C DP and 60 % RH	17	5/20
A2	10-35	18-27	- 12 °C DP and 8 % RH to 21 °C DP and 80 % RH	Same as A1	21	5/20
A3	5-40	18-27	- 12 °C DP and 8 % RH to 24 °C DP and 85 % RH	Same as A1	24	5/20
A4	5-45	18-27	- 12 °C DP and 8 % RH to 24 °C DP and 90 % RH	Same as A1	24	5/20

3(1)(l): The idle state power at the higher boundary temperature of the operating conditions class is 339.13 W.

3(1)(m): The active state efficiency and performance is 73.9.

3(1)(n): There are two methods by which a user can securely delete data from this system. The user performing secure data deletion should be an IT professional.

The first is with a Unified Extensible Firmware Interface (UEFI) shell utility. This utility works on R13 motherboard series with onboard SATA/NVMe devices. Any user may access and download this utility through following link:
https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9_Secure_Data_Deletion_Utility/

Download the shell utility package and extract it to a USB flash drive, then plug the drive into the server for which secure data deletion is necessary. Then turn the system on. Navigate to the BIOS setup menu, then place the server system into the UEFI shell environment. Follow the instructions in the README file to invoke the utility and complete the deletion.

The second method is through the secure data deletion tool provided by the original manufacturer of the hard drive. This should be used in a scenario where the shell utility is not applicable. Each manufacturer should have the tool available on their website. If needed, please look on the hard drive label for the name of the manufacturer and model information.

3(1)(o): List of recommended combinations of blade servers with chassis: N/A.

3(1)(p): List of all current SKUs within this product family: ARS-211M-NR.

3(3)(a): There is no use of cobalt in batteries in this product.

The indicative weight range of neodymium in the HDD is 0.0 if manufactured by Western Digital, and is between 5-25 grams if manufactured by Seagate.

3(3)(b): Please see the disassembly instructions on the next page.

Illustrated System Disassembly Instructions

Please note: All the illustrations in the below disassembly instructions are for demonstration only. Components shown here may not match exactly with the components in your system.

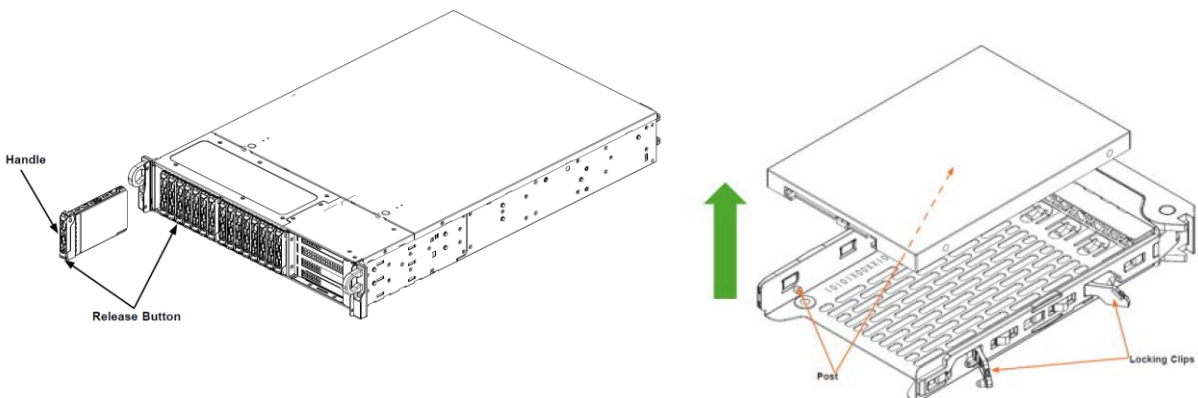
CAUTION: Always power off the system and unplug the power cord(s) first before disassembling the system!

1. Data Storage Devices

Type and number of fastenings: One (1) latch and two (2) locking clips.

Tools required: None.

Procedure: Push the release button on the carrier. Swing the handle fully. Grasp the handle and pull the drive carrier out of its bay.

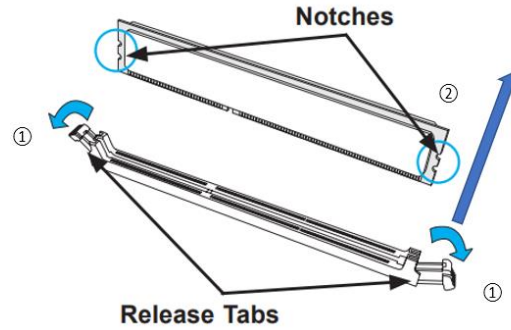


2. Memory

Type and number of fastenings: Two (2) latches per memory module.

Tools required: None.

Procedure: Press both release tabs on the ends of the memory module to unlock it. Once the module is loosened, remove it from the memory slot.



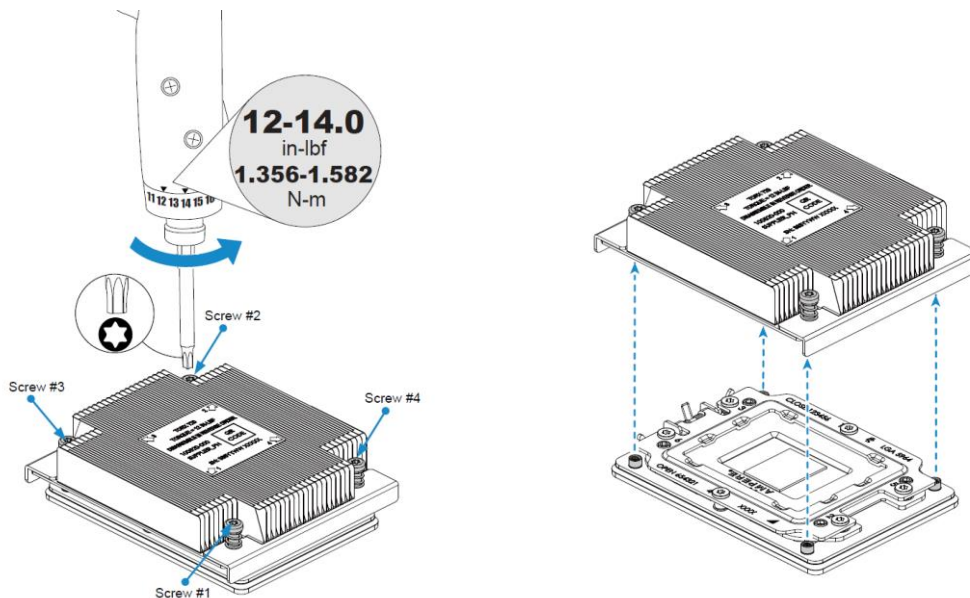
3. Processor

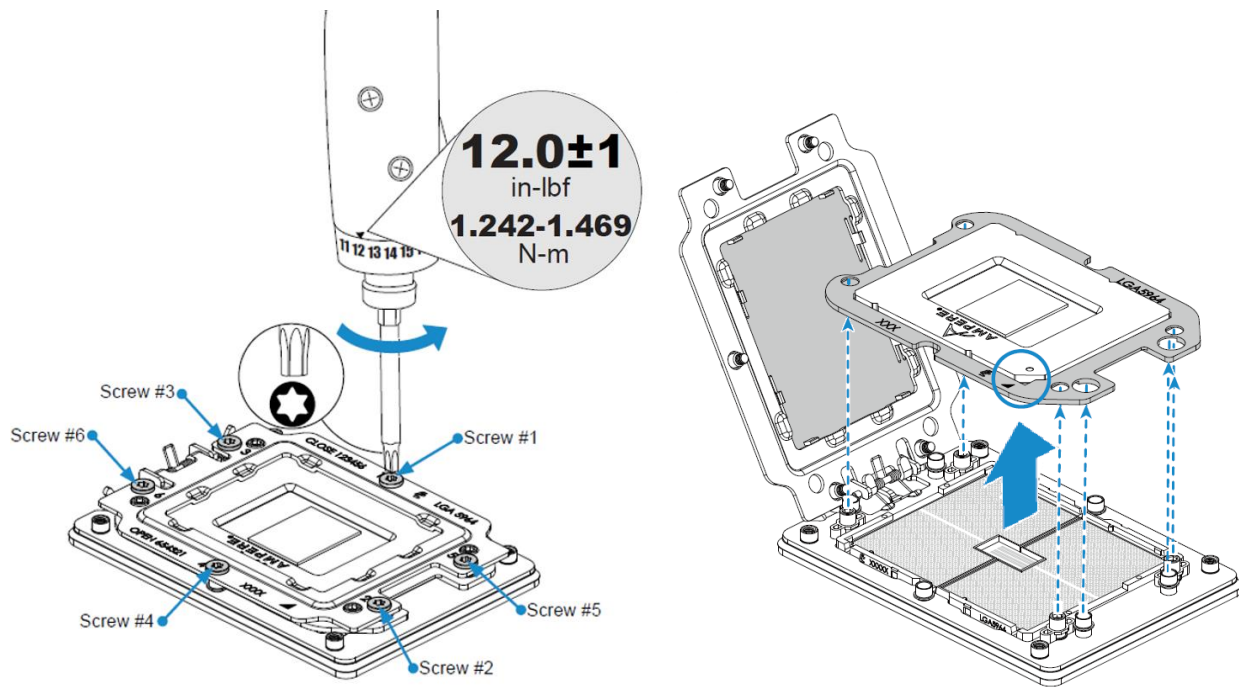
Type and number of fastenings: Four (4) T20 screws and six (6) T20 screws.

Tools required: Torque screwdriver with T20 bit.

Procedure:

1. Loosen the four T20 screws from the heatsink in the sequence 1-2-3-4, and lift the processor heatsink module off the processor socket.
2. Loosen the six T20 screws holding down the socket force frame in the sequence of 6-5-4-3-2-1, as in the illustration below. When the socket force frame is open, remove the processor from the socket.



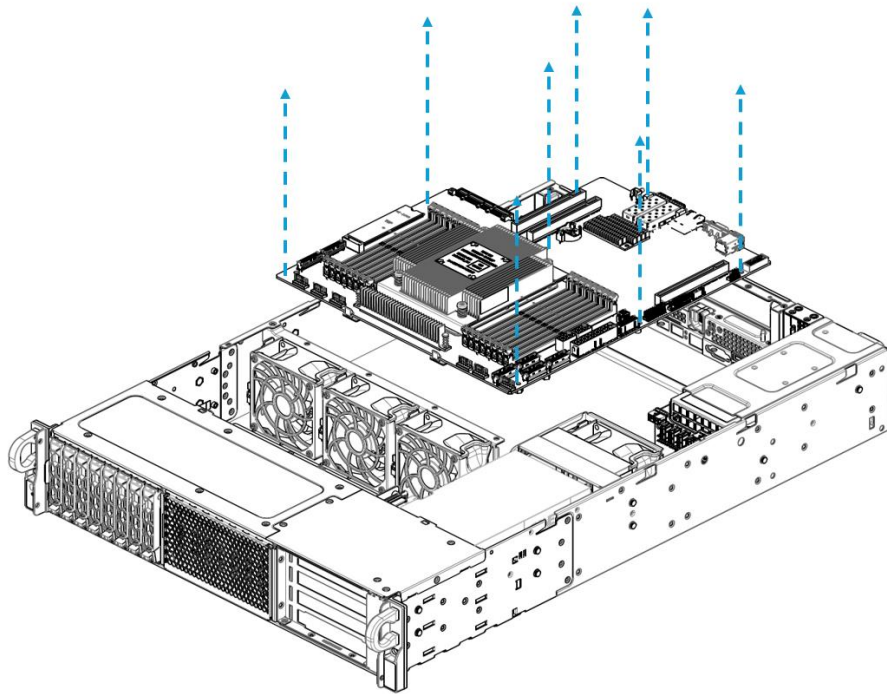


4. Motherboard

Type and number of fastenings: Eight (8) Phillips screws.

Tools required: Phillip #1 screwdriver.

Procedure: Remove all eight Phillips screws. Lift the motherboard from its base.

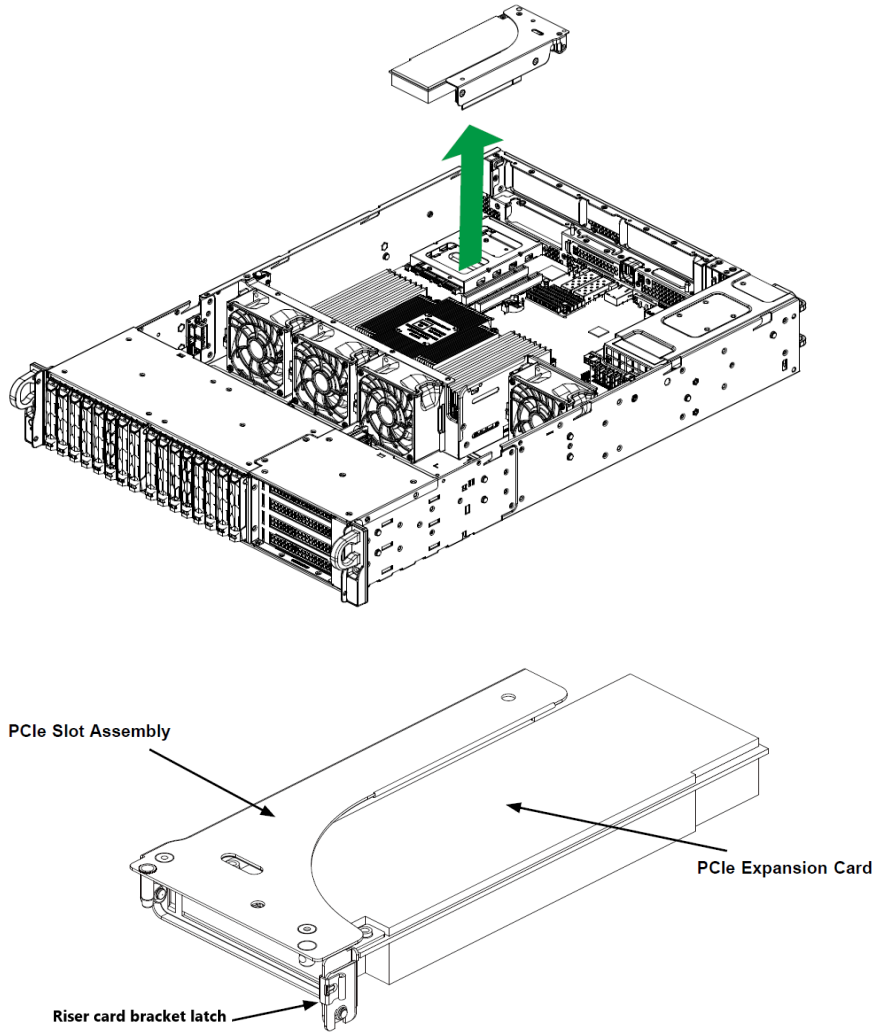


5. Expansion Card

Type and number of fastenings: One (1) latch per riser card bracket.

Tools required: None

Procedure: Lift the riser card bracket(s) out of the chassis using the pull tabs. Open the riser card bracket latch, and insert the expansion card onto the riser card.



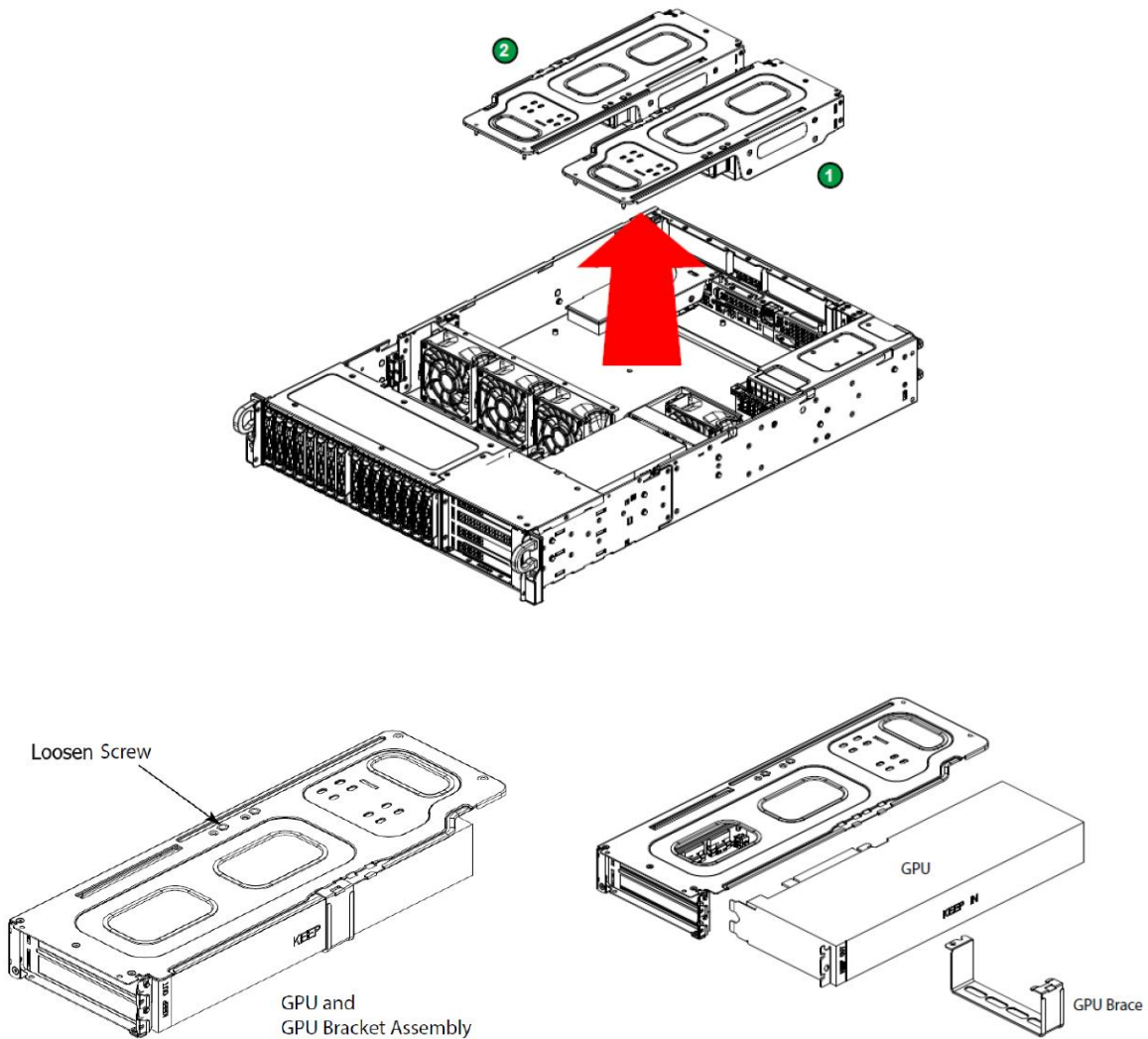
6. GPU Card (Rear of Chassis)

Type and number of fastenings: Two (2) latches and one (1) Philips screw per GPU bracket.

Tools required: Phillips screwdriver with PH2 bit.

Procedure:

1. Lift the GPU bracket up and away from the system.
2. Remove the GPU brace by loosening the screw holding down the GPU brace.
3. Open the GPU bracket latches and remove the GPU card from the riser card slot.



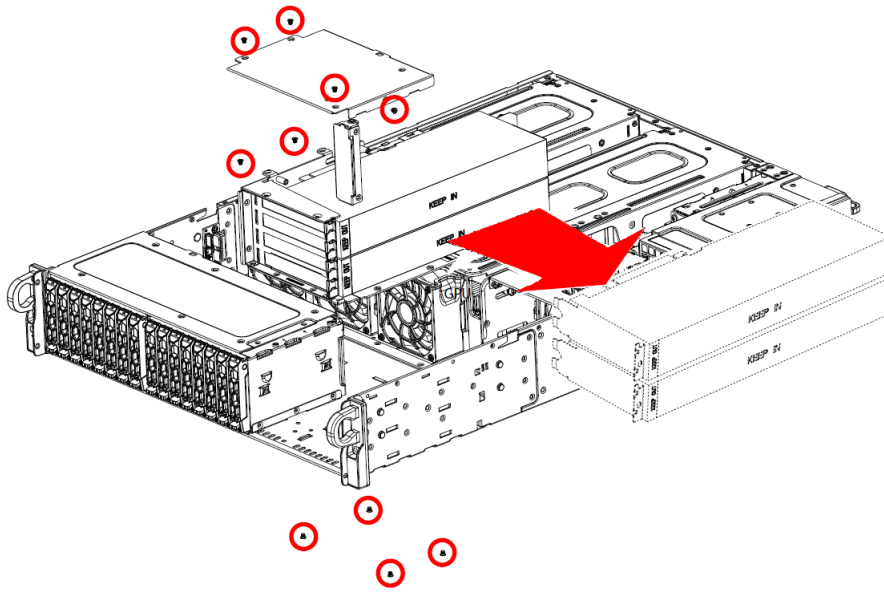
7. Graphics Card (Front of Chassis)

Type and number of fastenings: Two (2) latch per riser card slot, and ten (10) Phillips screws.

Tools required: Phillips screwdriver with PH2 bit.

Procedure:

1. Remove four screws at the bottom of the chassis.
2. Remove six screws from the PCIe/GPU bracket module.
3. Pull the PCIe/GPU bracket module up, open the GPU bracket latch, and remove the GPU card from the riser card slot.

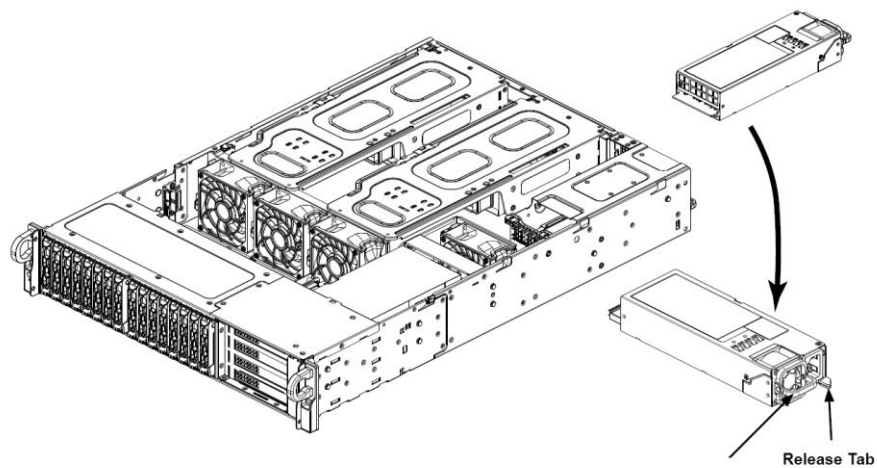


8. Power Supply Module

Type and number of fastenings: One (1) latch per module.

Tools required: None.

Procedure: Unplug the power cord from the power supply. Push the release tab on the back of the power supply module to the side and pull the module straight out.

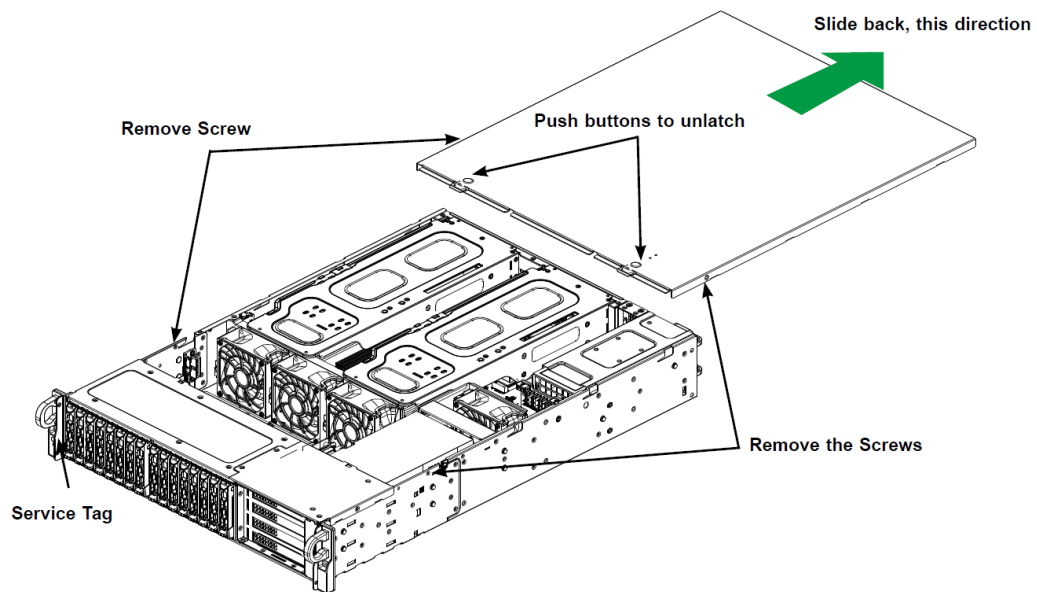


9. Chassis Cover

Type and number of fastenings: Two (2) Phillips screws.

Tools required: Phillips screwdriver with PH2 bit.

Procedure: Remove the two screws on the sides of the chassis. Hold down the two buttons simultaneously while sliding away the chassis cover.

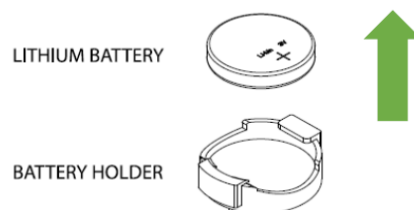


10. Batteries

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure: Push aside the small clamp that covers the edge of the battery. When the battery is released, lift it out of the holder.

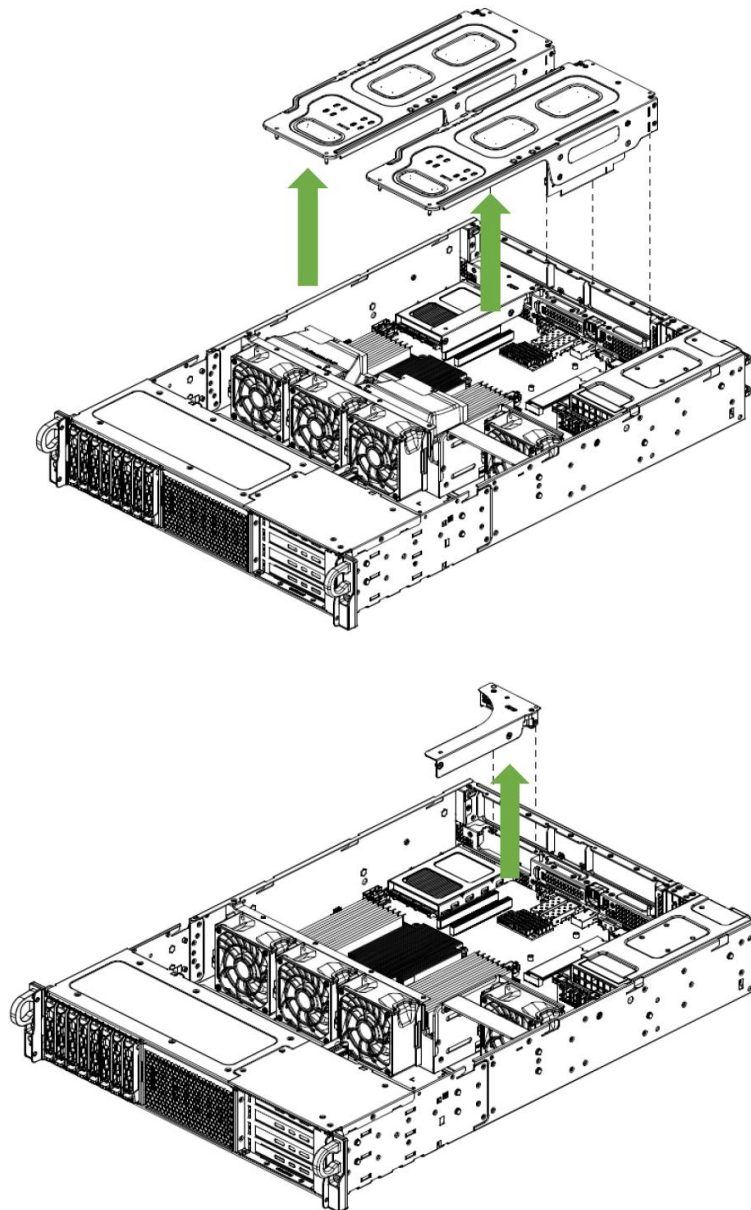


11. Riser Card

Type and number of fastenings: None.

Tools required: None.

Procedure: Lift the GPU brackets and riser card bracket up from the motherboard expansion slots.



12. Fans

Type and number of fastenings: One (1) fan header per fan, and one (1) latch per fan.

Tools required: None.

Procedure: Disconnect the fan wiring from the fan header on the motherboard. Push the release latches and lift the fan up from the housing and out of the chassis.

